

Title (en)
SYSTEM FOR PROCESSING WAFERS

Title (de)
ANLAGE ZUR BEARBEITUNG VON WAFERN

Title (fr)
SYSTEME DE TRAITEMENT DE TRANCHES

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Application
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Abstract (en)
[origin: DE19921244A1] The invention relates to a system for processing wafers in at least one clean room (1). The inventive system comprises an arrangement of production units (2) for carrying out individual production steps and a transport system for transporting the wafers between different production units (2). Furthermore, at least one control station (7) is provided for automatically tracking and controlling the material flow of the wafers. Process data is read in the control station (7) by the production units (2) and/or the transport system.

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